

General Description

The WSD75100DN56 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD75100DN56 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

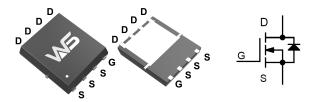
Product Summery

BV _{DSS}	R _{DSON}	I _D
75V	5.3mΩ	100A

Applications

- DC-DC converter switching for Networkong
- General purpose switching

DFN5X6-8 Pin Configuration



Absolute Maximum Ratings (T_A=25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	75	V
V_{GS}	Gate-Source Voltage	±25	V
TJ	Maximum Junction Temperature	150	°C
I _D	Storage Temperature Range	-55 to 150	°C
Is	Diode Continuous Forward Current,T _C =25°C	50	A
	Continuous Drain Current, V _{GS} =10V,T _C =25°C	100	А
I _D	Continuous Drain Current, V _{GS} =10V,T _C =100°C	73	А
I _{DM}	Pulsed Drain Current ,T _C =25°C	400	А
5	Maximum Power Dissipation,T _C =25°C	155	W
P_D	Maximum Power Dissipation,T _C =100°C	62	W
D	Thermal Resistance-Junction to Ambient ,t =10s`	20	°C
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient ,Steady State	60	°C
$R_{ heta JC}$	Thermal Resistance-Junction to Case	0.8	°C
I _{AS}	Avalanche Current, Single pulse,L=0.5mH	30	Α
E _{AS}	Avalanche Energy, Single pulse,L=0.5mH	225	mJ



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	75			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.043		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =25A		5.3	6.4	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2.0	3.0	4.0	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-6.94		mV/℃
I _{DSS}	Drain-Source Leakage Current	V_{DS} =48V , V_{GS} =0V , T_J =25 $^{\circ}\mathrm{C}$			2	- uA
		V_{DS} =48V , V_{GS} =0V , T_{J} =55 $^{\circ}\mathrm{C}$			10	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V_{DS} =5V , I_D =20A		50		S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.0	2	Ω
Q_g	Total Gate Charge (10V)	V _{DS} =20V , V _{GS} =10V , I _D =40A		65	85	
Q_{gs}	Gate-Source Charge			20		nC
Q_{gd}	Gate-Drain Charge			17		1
$T_{d(on)}$	Turn-On Delay Time			27	49	
Tr	Rise Time	V_{DD} =30V , V_{GEN} =10V , R_{G} =1 Ω ,		14	26	no
$T_{d(off)}$	Turn-Off Delay Time	I _D =1A ,RL=15Ω.		60	108	ns
T _f	Fall Time			37	67	
C _{iss}	Input Capacitance	V _{DS} =20V , V _{GS} =0V , f=1MHz	3450	3500	4550	
Coss	Output Capacitance		245	395	652	pF
C _{rss}	Reverse Transfer Capacitance		100	195	250	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.5mH , I _{AS} =30A	198			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			50	Α
I _{SM}	Pulsed Source Current ^{2,6}	VG-VD-UV , FOICE Cullelli			100	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =20A , T_{J} =25 $^{\circ}$ C			1.4	V

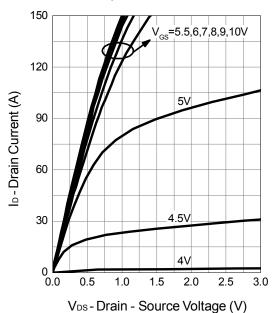
Note

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec .
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.5mH,I_{AS}=30A
- 4.The power dissipation is limited by 150 $^{\circ}\mathrm{C}$ $\,$ junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.
- 7.Package limitation current is 100A.

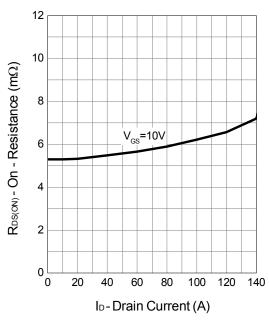


Typical Characteristics

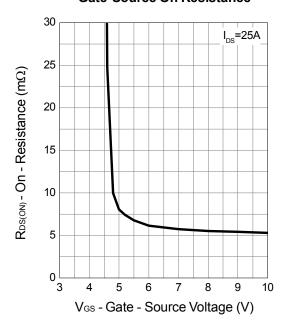
Output Characteristics



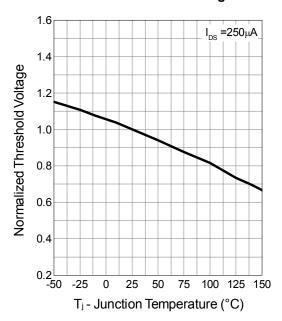
Drain-Source On Resistance



Gate-Source On Resistance

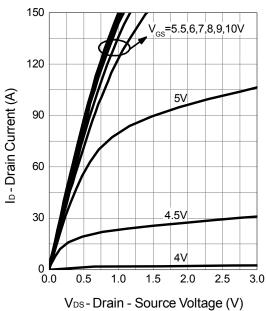


Gate Threshold Voltage

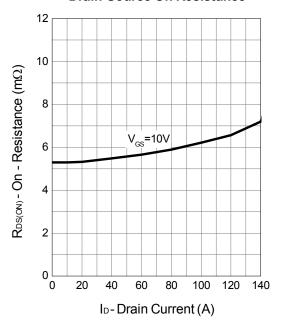




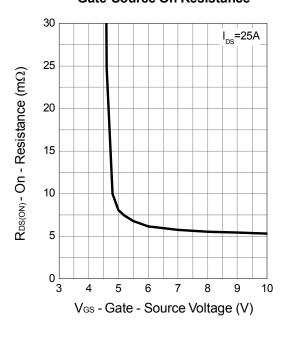




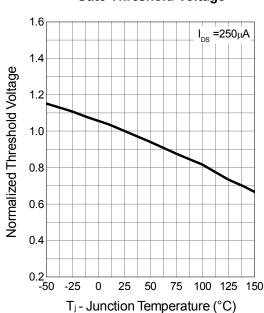
Drain-Source On Resistance



Gate-Source On Resistance

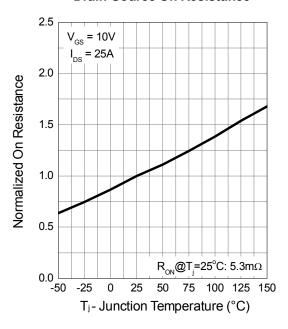


Gate Threshold Voltage

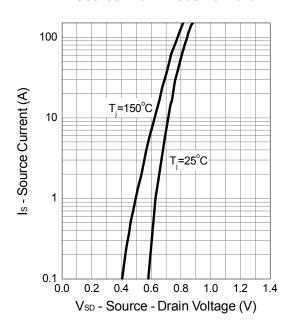




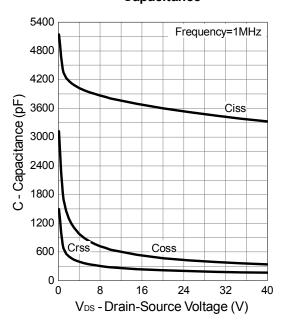
Drain-Source On Resistance



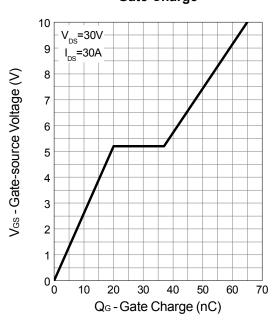
Source-Drain Diode Forward



Capacitance



Gate Charge





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